

IICIE 2026

International Integrated Circuit Innovation Expo

 **September 9-11, 2026**

 **Shenzhen World**
Exhibition & Convention Center

Exhibition Area

60,000 m²

Exhibitors

1,100 ⁺

Visitors

60,000 ⁺



Booth Application



Visitor Registration



IICIE

INTERNATIONAL
INTEGRATED CIRCUIT
INNOVATION EXPO

International Integrated Circuit Innovation Expo (IICIE 2026) is a premier platform for the global semiconductor industry, fostering collaboration across the entire value chain, encompassing **chip & IC design, manufacturing & packaging equipment, materials and parts**. It brings together key players from IDM, Fabless, Fab, and OSAT, while attracting professionals from AI, consumer electronics, automotive, communications and computing, display, optoelectronics, and new energy.

By facilitating face-to-face engagement, precise business matchmaking, and knowledge exchange, IICIE 2026 stands as a key event for industry leaders and innovators, empowering innovation and value for the entire semiconductor ecosystem.



Highlights

01

Building a Comprehensive Semiconductor Ecosystem

This expo showcases the entire semiconductor value chain, including chip & IC design, semiconductor manufacturing, packaging & testing equipment, materials and parts. This comprehensive display highlights manufacturing processes and breakthrough innovations across the integrated circuit industry, with participation from leading companies including UAHONG SEMICONDUCTOR, TONGFU MICROELECTRONICS, SKYVERSE, BYD Semiconductor, etc.

02

Focus on Chips and Cross-Border Applications

The expo showcases AI chips, communication chips, storage chips, CPU chips, sensor chips, analog chips, digital chips, power management and power devices, RF chips, motor drive chips, etc. Featured key exhibitors include UNISOC, ZTE MICROELECTRONICS, INGENIC, C*CORE XMC, EMPYREAN, etc.

03

Focus on Integrated Circuit Applications & Emerging Markets

The event combines exhibition with high-level knowledge exchange through industry and application forums. Through high-end seminars, technical exchanges, project matchmaking, and capital linkage, the expo will comprehensively facilitate the integration of IC industry resources and innovative collaboration.

**The above is a partial list of companies in no particular order.*

Themed Halls

IC Products, Packaging and Testing

- IC Chip
- IC Design / Electronic Design
- EDA & IP
- OSAT
- Packaging Equipment / Testing Equipment
- Packaging Material and Consumable / Core Parts
- Featured Zone (AI Computing Power and Application, Advanced Packaging, Advanced Computing)

IC Fabrication

- IC Fabrication & Foundry
- IC Manufacturing Equipment
- IC Metrology Equipment
- Substrate & Manufacturing Material & Consumables
- Core Parts
- Featured Zone (Achievements from Universities & Research Institutes)

Compound Semiconductor

- Power Device & Module
- Material & Substrate
- Manufacturing Equipment
- Packaging & Testing Equipment
- Core Parts
- Featured Zone (Automotive Chip and Power Semiconductor)

Exhibit Profile



Chip

AI Chip, Communication Chip, Memory Chip, CPU Chip, Sensor Chip, Analog Chip, Digital Chip, Power Management and Power Chip, RF Chip, Driver Chip, etc.



IC Design / Manufacturing Service

IP/EDA, Fables, Foundry, OSAT (Outsourced Semiconductor Assembly and Testing), Testing Services, etc.



Semiconductor Equipment

Manufacturing Equipment, Packaging Equipment, Inspection and Testing Equipment, Assembly Equipment, Environmental Control Equipment, Factory Automation / Robot, etc.



Semiconductor Material

Substrate Material, Manufacturing Material, Packaging Material, etc.



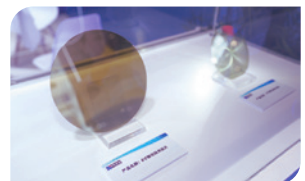
Semiconductor Core Parts

Sealing Ring, Precision Bearing, Metal Part, Quartz / Silicon / Sic (Silicon Carbide) / Ceramic Component, Power Supplies (RF Power Supply, DC Power Supply, Plasma Power Supply, etc.), Stepper Motor / Motion Control / Servo Motor, Pump / Semiconductor Valve / Pressure, Electrostatic Chuck, Flow Meter, Machine Vision, Sensor, Linear Motor, etc.



Compound Semiconductor and Power Device

Silicon Carbide (SiC), Gallium Nitride (GaN), Diamond, Gallium Oxide (Ga_2O_3), Cubic Boron Nitride (cBN), Aluminum Nitride (AlN), Graphite & Carbon Material, Power Device, etc.



Key Exhibitors

Chip and IC Design



Power Semiconductor



Semiconductor Material



Compound Semiconductor



Wafer Fabrication / Advanced Packaging



Semiconductor Equipment



Semiconductor Core Parts



*The above is a partial list of exhibitors in no particular order.

2025 Facts & Figures



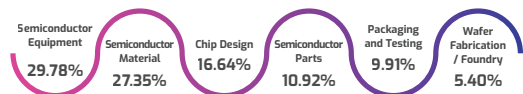
Part of Overseas Visitor Countries



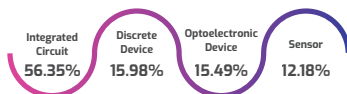
Visitor Analysis



Semiconductor Fabrication and Service



Semiconductor Product



Key Visiting Company

EDA/IP

ACTT, EMPYREAN, HCHIPLT SEMICONDUCTOR, PRIMARIUS, RONG SEMICONDUCTOR, SEMITRONIX, SICHIP, SIEMENS EDA, SPLENDOR, SYNOPSIS, UNIVISTA, XPEEDIC...

Fabless & IDM

BASIC SEMICONDUCTOR, BIWIN, BYD, C-CORE, CHIPON MICROELECTRONICS, CHIPPACKING, CXMT, DOSILICON, ELLON, EVERBRIGHT, FINE MADE MICRO, GEEHY, GOOGLE, GOFORMICRO, GOODIX, GUOXIN MICRO, HANWEI ELECTRONICS, HISILICON, IBM, INTELLIFUSION, KAIFA, LONGSYS, NSING, NVIDIA, SANAN, OPTOELECTRONICS, SANECHIPS, SGKS, SIGMASTAR, SILAN, SONY, STARFIVE, STMICROELECTRONICS, STS, UNISOC, VALEO, VIMICRO...

Foundry

CR MICRO, GLOBALFOUNDRIES, HUAHONG, NEXCHIP, SAMSUNG FOUNDRY, SMIC, HLMC, TOWER SEMICONDUCTOR, PENGXINWEI...

OSAT

BLUE ROCKET ELECTRONICS, CAPCON, CHIPMORE, CHIPPACKING, FHCC, GUANGDONG 3D-SEMI, HISEMI, HT-TECH, JCET, KAIFA, LEADYO, NCP CHINA, SHENGYUAN SEMICONDUCTOR, SINOIC, SJ SEMI, TIANCHENG, TONGFU MICROELECTRONICS, UNIONSEMICON, V-TEST, WISE ROAD CAPITAL, WLCCSP, YUNTIAN...

Compound Semiconductor

PUSHING, CCMC, DOGAIN, ICEMOS, PURECHIP, SICC, TANKEBLUE, ZINGSEMI...

Power Semiconductor

AST, ASCENPOWER, BELLING, INVSEMI, INVT, JIMICROELECTRONICS, MITSUBISHIELECTRIC, MURATA, NEXPERIA, TBEA, UNIMICRON, WEEN SEMICONDUCTORS...

Sensors

EZVIZ, HESAI, HUALIAN ELECTRONICS, LENS TECHNOLOGY, OMRON, RAPHAEL OPTECH, RAYTRON, SENSYLINK...

Intelligent Equipment

AUTOWELL, BOZHON, CHUANYI, EMERSON, GOOGOLTECH, HCFA, HEYAN, INNO LASER, JAFENG AUTOMATION, KALJO, KERUIDA, KEYENCE, LEAD, NASO TECH, NCGPOWER, NEXTOOL, OPT, OPT, SINEVA, SISCANTECH, TENSUN, TORCH, TZTEK, YAMAHA, YITOA, ZC OPTOELECTRONIC, ZHAOYANG SUNSHINE TECHNOLOGY...

Industrial Robot

ASTRIBOT, EAVISION, ELITE ROBOTOS, FANUC, LEADSHINE, MEGAROBO, MEGMEET, SCHNEIDER ELECTRIC, SIASUN, STEP, TOPSTAR, UBTECH...

Printed Circuit Board Manufacturing / Assembly

ASUS, AVARY HOLDING, FASTPRINT, KINWONG, LUXSHARE, MANKUN TECHNOLOGY, MFS TECHNOLOGY, RAYTRONS, RED BOARD, SCC, SHUI FUJI ELECTRONICS, UNIMICRON TECHNOLOGY...

Automotive

BAOLONG, BMW, BYD, DENSO, DESAY SV, GAC TOYOTA, NIO, SAIC, SGMW, UAEF, XINJIEAN, ZEEKR...

Semiconductor Equipment

AFILM, AIT, ALLSEMI, ASPIRING, CCTECH, CETC 13, CETC 45, CHOTEST, DJEL, DREAM LAUNCH, FM5H, GLOBALFOUNDRIES, HAYUE SEMICONDUCTOR, HSET, HUATUO SEMICONDUCTOR, HUAV, HWATSING, HYMSON, KINGSEMI, LEIBOSEMI, LIANDE, MACROTEST SEMICONDUCTOR TECHNOLOGY, MAGIC-RAY, MAXWELL, MINTEST, MOSART, MQL, NASO TECH, NEXCHIP, S C NEW ENERGY TECHNOLOGY, SIDA, SKYVERSE, SUNNY INSTRUMENTS, TAIYAN SEMI EQUIPMENT, T-VISION, XINWICHANG TECHNOLOGY, YUWETEK, ZHENGYE TECHNOLOGY, ZHIZHENG HOLDING...

Semiconductor Material

ANCHUTECH, CCTC, DINGLONG, ESWIN, GEMCH, GRIKIN, HUALUN CHEMICAL, HUATE GAS, JINGJIUMC, KFMI, LUYUANSICI & TECH, MITSUI HIGH-TEC, NATA OPTO-ELECTRONIC MATERIAL, NEWWAY, PERIC, QINGYI, RONGDA, SINOPACK ELECTRONIC, SINYANG SEMICONDUCTOR, SQ GROUP, SUNTIFIC, SYTECH, TDG, WANHUA CHEMICAL, YIXIN SEMICONDUCTOR, ZHONGWEI LIHE...

Semiconductor Core Parts

AMS, BWT, COHERENT, FORTUNE PRECISION, GENTECH, GLOBAL TECHNOLOGY, GZ PHOTONICS, HANBELL, INNO LASER, JIENUOTE, KFMI, KINGLAI, KSTAR, MILOPTIC, OFILM, SCHAEFFLER, SHUIJA PHOTONS, TZTEK, U-PRECISION, VITAL MATERIALS...

Display

BOE, HONGLI ZHIHUI, HORION, INNOLUX, JCOPTIX, JZETEK, KONKA, LEYARD, LIGHTNING OPTOELECTRONIC, MLS, NATIONSTAR, OKTECH, REFOND, TCL CSOT, UNILUMIN, WOLFSPEED, XINGYU...

New Energy

BAK, CGN, DESAY, HUAWEI DIGITAL POWER, INNER MONGOLIA PHOTONICS TECHNOLOGIES, JA SOLAR, SUNWODA, TBEA...

Computing & Communications

ALIBABA CLOUD, BAIDU, BYTEDANCE, CHINA MOBILE, CHINA TELECOM, CHINA UNICOM, DIGITAL CHINA, FIBOCOM, HUAWEI, INSPUR, JD, MEITUAN, OFIDE, QUECTEL, TENCENT, ZTE...

Optoelectronics

ACCELINK, AFR, APPOTRONICS, C-DATA, ELSTECH, EOPTOLINK, EVERPROX, FINISAR, HI-OPTEL TECHNOLOGY, HISENSE, HISILICON, O-NET, OPLINK COMMUNICATIONS, OPTOWIDE, PHOENIX TELECOM TECHNOLOGY, PHOTONX TECHNOLOGY, RAYCUSLASER, SDGI, SOURCE PHOTONICS, TFC, TRIPLE-STONE, XHB ELECTRONICS TECHNOLOGY, YTOT, ZHONGJI INNOLIGHT...

Consumer Electronics

CHINASOFT INTERNATIONAL, DELTA, DJI, ECOVACS, EMDOR, GOOVIS, HISENSE, HSAE, HUAWEI, IFLYTEK, INSTA360, JD, LITTLE GENIUS, LLVISION, LONGCHEER, MAGIC LEAP, MIDEA, NOKIA, OPPO, ORVIVO, ROIDMI, SENNHEISER, SHENHAO TECHNOLOGY, TCL, TRANSNION, VIVO, WELLRUN TECHNOLOGY, XIAOMI...

University / Research Institute

BIT, BUJT, BUAA, CAEP-IEE, CAS GDAS, CAS-CIOMP, CAS-SIAT, CAS-XIOPM, CEPREI, FDU, GDUT, HIT, HUST, IIE CAS, IOP CAS, IS CAS, JHL, JNU, PKU, SCUT, SIOM, SUSTECH, SZU, THU, TJU, WHU, XMU, ZJU...

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VIP Buyer Program

Exclusively designed for key buyers and senior decision makers in the semiconductor industry with specific sourcing needs or purchasing plans, this program offers personalized, one-on-one service to efficiently connect buyers with suitable exhibitors and products. Onsite VIP privileges are provided to facilitate seamless one-on-one procurement meetings between buyers and IICIE exhibitors, ensuring a streamlined and productive experience.

Exclusive Privileges

- Publish your sourcing requirements to attract qualified exhibitors and enhance sourcing efficiency.
- Gain first-hand Visitor Guide and Exhibitor List before the show.
- Enjoy business matchmaking services, including complimentary meeting rooms.
- Get priority invitations to exclusive networking events (Gala Dinner, Happy Hour, etc.).
- Access the onsite VIP Lounge, offering refreshments, tea and coffee.
- No queue for badge pick-up at the VIP Buyer counter.



Concurrent Conferences & Events

Leadership Summit

2026/9/9	2026 International Integrated Circuit Innovation Expo Opening Ceremony & Integrated Circuit Innovation Forum
2026/9/10	1st Integrated Circuit Product and Application Collaborative Innovation Conference
2026/9/10-11	IWAPS International Workshop on Advanced Patterning Solutions

Themed Summit

2026/9/9 - PM	1st China Integrated Circuit Innovation Investment Conference
2026/9/9 - PM – 2026/9/11 - AM	Global Semiconductor Analysts Conference

Chip and Chip Application

2026/9/9 - PM	2026 China RISC-V Ecosystem Conference
2026/9/9 - PM	3rd AI-Enabled Consumer Electronics Innovation Forum
2026/9/10 - AM	Secure Defense with Intelligence - AI Security Innovation Application and Industry Integration Conference
2026/9/10 - AM	Edge AI Chip Power: 2026 Smart Terminal Chip Ecosystem Summit
2026/9/10 - PM	Source of Intelligent Computing: 2026 Chip Computing Power Innovation Summit
2026/9/10	Chip Design Innovation & Development Forum
2026/9/10	Automotive Chip Industry Innovation Forum
2026/9/11 - AM	2nd Edge AI and Intelligent Control Technology Industry Forum
2026/9/11 - AM	EDA and IP Electronic Design Forum

Semiconductor Manufacturing

2026/9/9 - PM	Advanced Material Innovation Forum – Breaking Through the Limits - Key Materials for AI Heterogeneous Integration Packaging
2026/9/9 - PM	Core Semiconductor Manufacturing Equipment and Components Development Forum

Advanced Packaging and Testing

2026/9/10	Advanced Packaging & Testing Technology Forum – From CoWoS to CoPoS: Exploration of Advanced Packaging Technology Evolution and Supply Chain Layout for AI Era
2026/9/11 - AM	2nd CPO & Heterogeneous Integration Technology Symposium

Intelligent Manufacturing

2026/9/9 - PM	Machine Vision and Intelligent Manufacturing Innovation Forum
2026/9/9 - PM	2026 Embodied Intelligence Industry Conference – From Computing Power to Execution, Building Embodied Intelligence Systems
2026/9/10 - PM	2026 Intelligent Manufacturing Innovation and Development Conference
2026/9/10	Intelligent Industrial Control Empowering Automation Innovation Forum

Green Facilities Management

2026/9/11 - AM	Green Manufacturing Innovation Forum
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Concurrent Events

2026/9/9 - PM	The 8th Fudan Micro Cup Electronic Design Contest Awards Ceremony
2026/9/10 - AM	1st China University Students AI-Enabled Innovation and Entrepreneurship Competition and Award Ceremony
2026/9/10 - AM	2026 China Semiconductor Materials Innovation and Development Conference
2026/9/10 - PM	New Technology and New Product Release Conference
2026/9/9 - AM	Integrated Circuit Equipment and Components Leading Enterprises Joint Seminar (Closed Meeting)
2026/9/9 - PM	Integrated Circuit Design Leading Enterprise Seminar (Closed Meeting)
2026/9/9 - PM	Demonstration Microelectronics Institute Industry-Academia Integration Development Alliance Council and Dean's Forum (Closed Meeting)
2026/9/9 - PM	Semiconductor Integrated Circuit Investment Leading Enterprises Seminar (Closed Meeting)

* Conference topics are subject to change.



Industry Technology Salon

Organized in collaboration with associations and media partners, these online and off-line new technology exchange salons are designed to support enterprises in promoting their brands throughout the year.

Chip and Chip Applications: Industrial Control, Consumer Electronics, AI, RISC-V, AR & VR, Memory Chip

Semiconductor Manufacturing: Advanced Packaging & Testing, Compound Semiconductor, Semiconductor Equipment

Intelligent Manufacturing: Precision Motion Control, Core Components, Intelligent Manufacturing Innovation

**Topics are subject to change*



Happy Hour

Gathering VIP buyers and exhibitor representatives, and focusing on in-depth industry networking, it creates a business exchange platform that balances a relaxed atmosphere with professionalism.

Gala Dinner

A premier networking event for the semiconductor industry, gathering domestic and international entrepreneurs, technology leaders, and senior industry figures. Attendees engage in interactive exchanges, share business insights, and gain valuable network resources.



Co-located Exhibitions: Creating a Mega Event Spanning 340,000 sqm

Fostering Complementary Upstream and Downstream Convergence, Gathering Diversified Professional Visitors

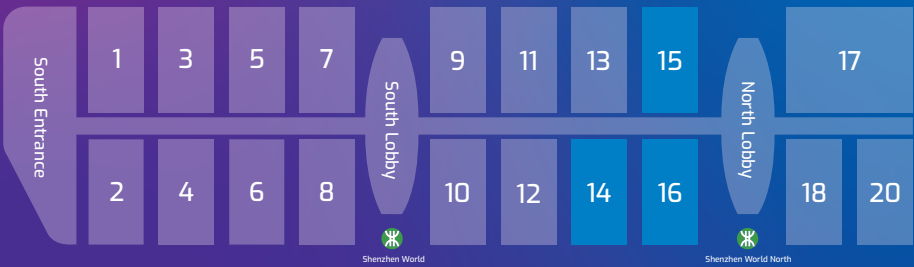
IICIE 2026 will be co-located with the **27th China International Optoelectronic Exposition (CIOE 2026)**, and **Shenzhen International Electronics & Embedded Expo (elexcon 2026)**. With a total exhibition area of **340,000 square meters**, these events are expected to gather over **5,000 exhibitors** and attract **240,000 professional visitors**. The goal is to drive in-depth convergence and collaborative development across key industries such as optoelectronics, integrated circuits, and electronics & embedded systems.

By leveraging the synergistic advantages of the three exhibitions, the event will showcase key technologies and resources, including **photonics / electronic chips, optical modules, optical lenses & modules, AR/VR, sensors, electronic components, and embedded systems**. It aims to provide a complete closed-loop ecosystem, spanning from **“Components - Chips, Modules - Solutions – Applications.”**




The three co-located exhibitions jointly build a global top-tier buyer ecosystem spanning **consumer electronics, intelligent automotive, robotics, AR/VR, communications, medical electronics, defense/security and display**, and catering channel resources of **solution providers, system integrators, agents, and distributors**. By integrating channel resources from solution providers, system integrators, agents, and distributors, they provide a one-stop platform for **R&D leaders, production and supply chain professionals, and technical decision-makers**.

Floor Plan



Contact Us

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Booth Application



Visitor Registration